

Using fluorinated and crosslinkable fullerene derivatives to improve the stability of perovskite solar cells

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SUPPORTING INFORMATION

Table 1. The fluorinated and crosslinkable fullerene derivatives, their application in PSCs, and device performance details.

| Fullerene derivative | Active layer | Role | J_{sc} (mA/cm ²) | V_{oc} (V) | FF (%) | PCE (%) | Stability | Ref. |
|---|---|-------------------------|--------------------------------|--------------|--------|---------|---|------|
| DF-C ₆₀ | CH ₃ NH ₃ PbI ₃ | Additive | 21.08 | 1.09 | 78.7 | 18.11 | 83% retaining in ambient (60±5% RH) after 1 month | [11] |
| DF-C ₆₀ | CH ₃ NH ₃ Pb _{0.5} Sn _{0.5} I ₃ | Additive | 26.1 | 0.87 | 69 | 15.61 | 50% retaining in ambient (60±5% RH) after 15 days | [12] |
| IS-1 | CH ₃ NH ₃ PbI ₃ | Additive | 16.7 | 1.03 | 69 | 11.8 | – | [13] |
| IS-2 | CH ₃ NH ₃ PbI ₃ | Additive | 16.1 | 1.06 | 73.8 | 12.7 | Nearly 80% retaining under AM1.5 simulated sunlight for 240 h | [13] |
| PI-1 | CH ₃ NH ₃ PbI ₃ | Additive | – | – | – | – | – | [13] |
| PI-2 | CH ₃ NH ₃ PbI ₃ | Additive | 16.1 | 1.02 | 69.4 | 11.7 | – | [13] |
| 3F-PC ₆₁ BM | CH ₃ NH ₃ PbI ₃ | Additive | 21.78 | 1.00 | 73.34 | 16.17 | 80% retaining after 550 h in N ₂ glove box | [14] |
| 5F-PC ₆₁ BM | CH ₃ NH ₃ PbI ₃ | Additive | 14.99 | 0.87 | 65.71 | 8.65 | – | [14] |
| C ₆₀ -PyF15 | CH ₃ NH ₃ PbI ₃ | Additive | 23.14 | 1.073 | 80.96 | 20.10 | 85% retaining in ambient (~35% RH) after 1440 h 81% retaining under N ₂ at 85 °C after 660 h | [15] |
| F-C ₆₀ | CH ₃ NH ₃ PbI _{3-x} Cl _x | CBL ^a | 21.2 | 0.97 | 75.4 | 15.5 | 80% retaining in ambient (20% RH) after 14 days | [16] |
| CF ₃ -PC ₆₁ BM | CH ₃ NH ₃ PbI ₃ | ETL ^b | 22.19 | 1.04 | 79.61 | 18.37 | 80% retaining at a room temperature after 25 days (40%–60% RH) | [17] |
| C ₆ F ₁₃ -PC ₆₁ BM | CH ₃ NH ₃ PbI ₃ | ETL | 21.90 | 1.05 | 77.02 | 17.71 | 80% retaining at a room temperature after 33 days (40%–60% RH) | [17] |
| CF ₃ -PC ₆₁ BM | CsFAMAPbI ₃ Br | ETL | 23.47 | 1.04 | 77.49 | 19.00 | – | [17] |
| C ₆ F ₁₃ -PC ₆₁ BM | CsFAMAPbI ₃ Br | ETL | 23.45 | 1.04 | 76.33 | 18.65 | – | [17] |
| FP-i | CH ₃ NH ₃ PbI _{3-x} Cl _x | ETL | 20.85 | 0.93 | 69.76 | 13.60 | 70%–85% retaining in air (40%–50% RH) after 70 h | [18] |
| FP-ii | CH ₃ NH ₃ PbI _{3-x} Cl _x | ETL | 21.40 | 0.93 | 71.55 | 14.23 | 70%–85% retaining in air (40%–50% RH) after 70 h | [18] |
| Sol-gel C ₆₀ | CH ₃ NH ₃ PbI _{3-x} Cl _x | ETL | 23.0 | 1.07 | 73 | 17.9 | – | [20] |
| PCBCB | CH ₃ NH ₃ PbI _{3-x} Cl _x | ETL | 22.4 | 1.11 | 73 | 17.9 | – | [20] |
| MPMIC ₆₀ | CH ₃ NH ₃ PbI ₃ | ETL | 20.2 | 1.08 | 64 | 13.8 | 10-fold and 14-fold enhancement in fracture resistance over PC ₆₁ BM and C ₆₀ | [19] |
| C-PCBSD | CH ₃ NH ₃ PbI _{3-x} Cl _x | Additive | 22.81 | 0.98 | 77 | 17.21 | 84.6% retaining in ambient (40±5% RH) after 180 h | [21] |
| C-PCBSD | CH ₃ NH ₃ PbI ₃ | Modify TiO ₂ | 21.1 | 1.12 | 79.0 | 18.7 | – | [22] |
| C-PCBSD: GD | CH ₃ NH ₃ PbI ₃ | Modify TiO ₂ | 23.30 | 1.11 | 78 | 20.19 | 80% retaining in ambient (25%–30% RH) after 500 h | [23] |
| PCBCB: CL | Cs _{0.05} (FA _{0.85} MA _{0.15}) _{0.95} -Pb(I _{0.9} Br _{0.1}) ₃ | ETL | 22.9 | 1.08 | 78 | 18.5 | 92% retaining of their stabilized power output after aging for 3000 h at 85 °C in N ₂ | [24] |
| C-PCBOD | CH ₃ NH ₃ PbI ₃ | Modify TiO ₂ | 23.99 | 1.041 | 73.25 | 18.29 | – | [25] |
| C-PCBOD | CH ₃ NH ₃ PbI ₃ | Additive | 22.60 | 1.14 | 79 | 20.4 | 72% retaining in ambient (20±5% RH) after 960 h | [26] |
| PCBM with DAZH | FA _{0.66} MA _{0.34} PbI _{2.85} Br _{0.15} | Modify TiO ₂ | 21.9 | 1.05 | 79.1 | 18.4 | – | [27] |

^a Cathode buffer layer; ^b Electron-transport layer.

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